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PATENT
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/829,161

Filed: April 9, 2001

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Confirmation No.: 8260

Examiner: H. Nguyen

Group Art Unit: 2812

Attorney Docket No.: 2269-3442.1US
(96-0428.01/US)

CERTIFICATE OF MAILING

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5/13/2003

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AMENDMENT UNDER 37 C.F.R. §1.116

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P. O. Box 1450
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Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed March 21, 2003, the three-month shortened statutory period for

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response to which expires on June 21, 2003. This response is submitted on or before two months from the mailing date of the Final Office Action.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 14 of this paper.